

CFS is specification applies
For the lead-free fuse series of thin film chip fuse.

●Features

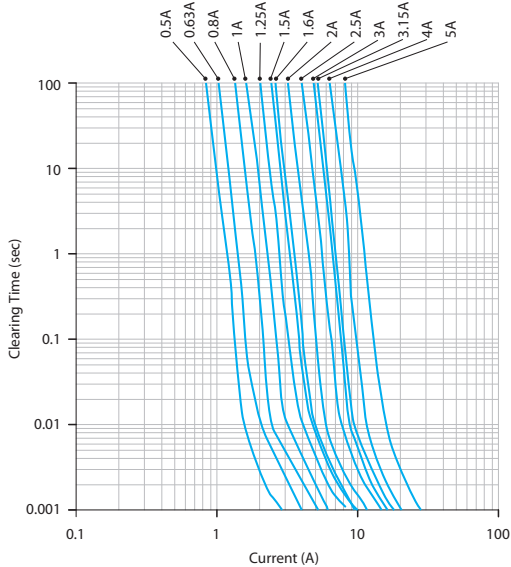
- Small and light chip current fuse for the secondary circuit
- Thin film manufacturing method stabilizing fusing characteristics
- Low power consumption less voltage dropping due to low internal resistance
- Suitable for over current protection of circuit block in small electronic device
- RoHS requirement

●Ampere Rating

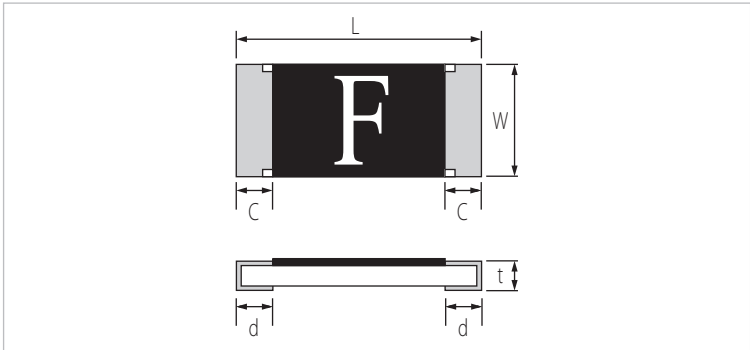
% of Ampere Rating	Opening Time
250%	5sec, Max.

●Average Time Current Curve

- CFS 06 Size



●Dimension




Type	Dimension (mm)				
	L	W	C	d	t
06 (0603)	1.6±0.1	0.8±0.1	0.3±0.2	0.35±0.2	0.45±0.1
12 (1206)	3.1±0.1	1.55±0.1	0.5±0.3	0.5±0.2	0.6±0.1

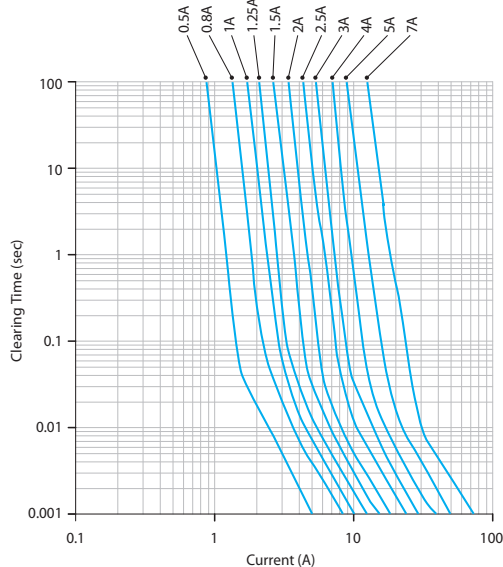
●Type Designation

CFS	06	V5	T	A500
Products Code	Size	Rated Voltage	Packaging	Rated Current
	06:0603(1.6X0.8mm) 12:1206(3.2X1.6mm)	V6 : 63V V5 : 50V V3 : 32V	T: Paper Tape(5K)	A500:0.5A

●Agency Approval

Agency	Item	File No.
	CFS 06 0.5A ~ 5A CFS 12 0.5A ~ 7A	E238986

- CFS 12 Size



●Characteristic

Part Number	Ampere Rating (A)	Voltage Rating (V)	Marking	Nominal Resistance Cold Ohms (mΩ)
CFS06V5TA500	0.50	DC50	F	175
CFS06V5TA630	0.63	DC32	I	130
CFS06V5TA800	0.80		K	93
CFS06V5T1A00	1.00		L	65
CFS06V5T1A25	1.25		M	47
CFS06V5T1A50	1.50		P	36
CFS06V5T1A60	1.60		N	34
CFS06V5T2A00	2.00		S	26
CFS06V5T2A50	2.50		T	20
CFS06V5T3A00	3.00		3	16
CFS06V5T3A15	3.15		U	15
CFS06V5T4A00	4.00		W	12
CFS06V5T5A00	5.00		Y	9
CFS12V6TA500	0.50	DC63	F	385
CFS12V6TA800	0.80		K	165
CFS12V6T1A00	1.00		L	108
CFS12V6T1A25	1.25		M	76
CFS12V6T1A50	1.50		P	51
CFS12V6T2A00	2.00		S	32
CFS12V3T2A50	2.50	DC32	T	26
CFS12V3T3A00	3.00		3	20
CFS12V3T4A00	4.00		W	14
CFS12V3T5A00	5.00		Y	10
CFS12V3T7A00	7.00		Z	6.5

●Performance

Test Items	Performance Requirements	Test Methods
Carrying Capacity	No fusing	Rated current, 4hr
Interrupting Ability	No Mechanical damages	After the fuse is interrupted, rated voltage applied for 30sec again
Bending Test	No Mechanical damages	Distance between holding points : 90mm, Bending : 3mm, 1time, 30sec
Resistance to Solder Heat	±20%	260℃ ±5℃, 10seconds ± 1second
Solder Ability	95% coverage minimum	235℃ ±5℃, 2 ± 0.5second 245℃ ±5℃, 2 ± 0.5second(Lead Free)
Temperature Rise	<75℃	100% of its rated current, Measure of surface temperature
Resistance to Dry Heat	±20%	105℃ ± 5℃, 1000hrs
Resistance to Solvent	No evident damages on protective coating and marking	23℃ ±5℃ of Isopropyl alcohol 90second
Insulation Resistance	10 ^{kΩ} and more	Measure DC resistance after fusing
Thermal Shock	ΔR<10%	-20℃/+25℃/+125℃/+25℃, 10cycle